## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

J.-S. Mok et al.

Attorney Docket No.: LEPA121687

Application No.: 10/677,182

Art Unit: 1792 / Confirmation No: 8329

Filed:

October 2, 2003

Examiner: S. Ahmed

Title:

METHOD OF FORMING SOLDER RESIST PATTERN

## AMENDMENT AFTER NON-FINAL REJECTION

Seattle, Washington 98101

February 15, 2008

## TO THE COMMISSIONER FOR PATENTS:

## **INTRODUCTORY COMMENTS**

Please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of the claims, which begins on page 2 of this paper.

Remarks/Arguments begin on page 9 of this paper.